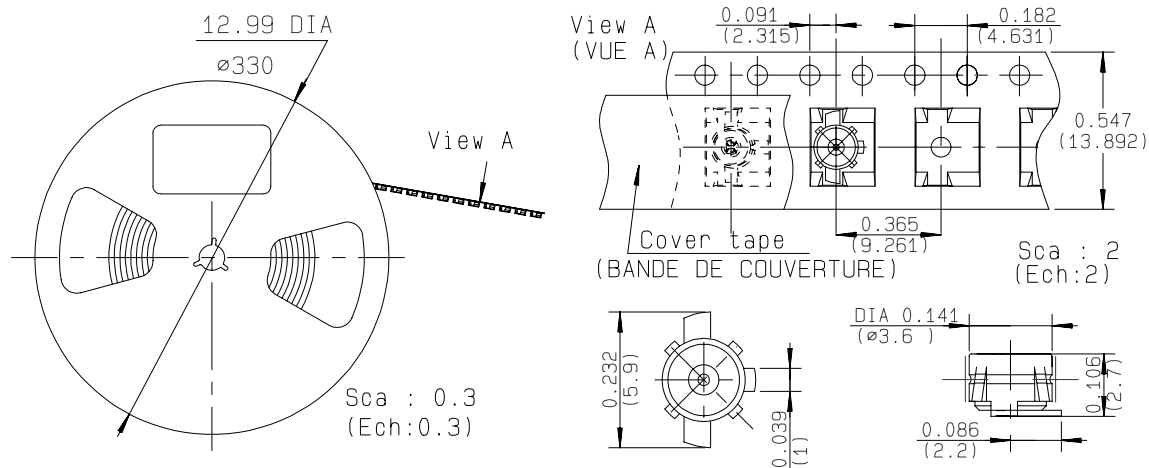


STRAIGHT JACK RECEPTACLE FOR PCB**SMT TYPE - GOLD 0.2 - REEL OF 100****R210.408.012**

Series : MMT



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY	PHOSPHOR BRONZE	GOLD 0.2 OVER NICKEL 2
CENTER CONTACT	BRASS	GOLD 0.2 OVER NICKEL 2
OUTER CONTACT	PHOSPHOR BRONZE	GOLD 0.2 OVER NICKEL 2
INSULATOR	PTFE	
GASKET	-	-
OTHERS PARTS	-	-
-	-	-
-	-	-

Issue : 0325 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



STRAIGHT JACK RECEPTACLE FOR PCB**R210.408.012****SMT TYPE - GOLD 0.2 - REEL OF 100**

Series : MMT

PACKAGING

Standard	Unit	Other
100	'W' option	Contact us

SPECIFICATION**ELECTRICAL CHARACTERISTICS**

Impedance	50	Ω
Frequency	0-8	GHz
VSWR	1.10 + 0.050	x F(GHz) Maxi
Insertion loss	0.20	$\sqrt{F}(\text{GHz})$ dB Maxi
RF leakage	- (NA)	- F(GHz)) dB Maxi
Voltage rating	170	Veff Maxi
Dielectric withstanding voltage	500	Veff mini
Insulation resistance	5000	M Ω mini

ENVIRONMENTAL

Operating temperature	-55/+100	$^{\circ}\text{C}$
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

OTHERS CHARACTERISTICS

Assembly instruction

Others :
accouplt : 18Nmax / desacc. : 7Nmin

MECHANICAL CHARACTERISTICS

Center contact retention	
Axial force – Mating end	NA N mini
Axial force – Opposite end	NA N mini
Torque	NA N.cm mini
Recommended torque	
Mating	NA N.cm
Panel nut	NA N.cm
Mating life	500 Cycles mini
Weight	0.100 g

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R210.408.012

Series : **MMT**

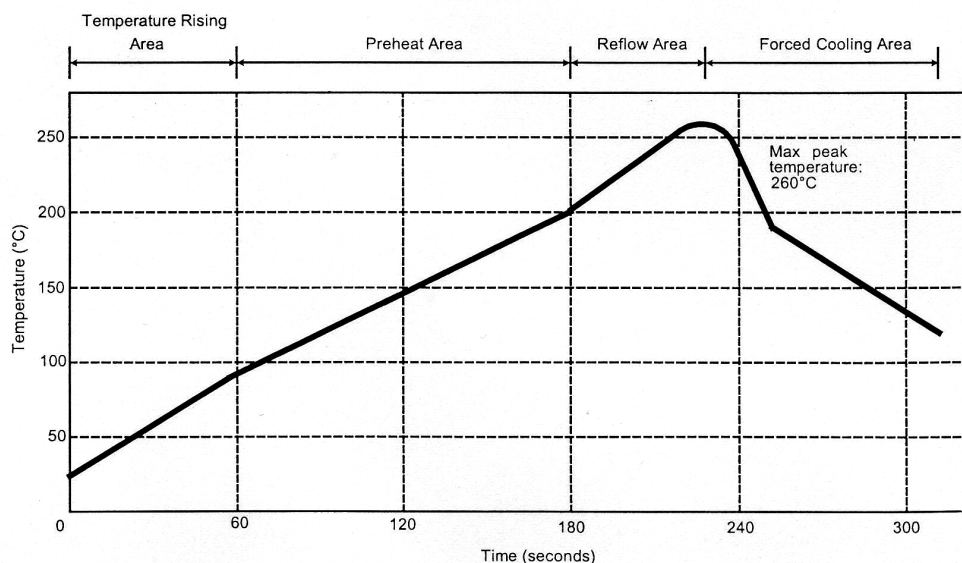
STRAIGHT JACK RECEPTACLE FOR PCB**SMT TYPE - GOLD 0.2 - REEL OF 100****R210.408.012**

Series : MMT

**SOLDER PROCEDURE OF MMT RECEPTACLE
IN INDUSTRIAL ENVIRONMENT**

- 1 – Deposition of solder paste Sn Ag4 Cu0.5 on mounting zone by screen printing application.
We recommend a Low Residue Solid Flux.
We advise a thickness of 200 microns (7.800 microinches). Verify that the edges of the prined zone are clean.
- 2 – Placement of the receptacle on the mounting zone with an automatic machine of « pick and place » type.
A video camera is recommended for positioning of the component. (see page 3)
Adhesive agents must not be used on the receptacle.
- 3 – Soldering by infra-red reflow.
Below, please find the typical profile to use.
- 4 – Cleaning of printed circuit boards
- 5 – Verification of solder joints and position of the component by visual inspection

Note : The MMT receptacle and the MMT plug must not be mated before completion of this procedure.



Parmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

Issue : 0325 A

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